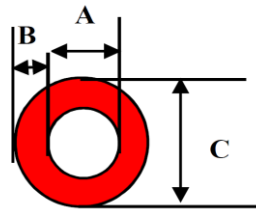


NC Drilling					
Layer Count	Minimum size(A)	Normal sizePAD(C)	Single side hole ring(B)	Minimum size PAD	
Double side	0.10mm	0.35mm	0.125mm	0.30mm	
1L+1L	0.15mm	0.40mm	0.125mm	0.35mm	
3L or more	0.15mm	0.45mm	0.15mm	0.4mm	
4L or more	0.2mm	0.5mm	0.15mm	0.45mm	
Flex-rigid	0.2mm	0.5mm	0.15mm	0.45mm	
Drilling size range			0.1mm~6.5mm		
Hole tolerance			±0.01mm		
True position size			±0.05mm		
Copper Plating					
Type	Copper weight range	Normal Capability		Special Capability	Remark
Sculptural	Copper Plating	300±100u"		400±120u"	
Double side				450±150u"	
1L+1L	10~30u"	600±200u"		800±250u"	
3L or more					
4L or more					
Flex-rigid					
Remark	Drilling Minimum siz 0.1mm · Aspect ratio8 : 1				
Etching					
Trace width / space	Layer Count	Copper Weight	Minimum trace width	Minimum trace space	Remark
	Singel side	1OZ	3mil	3mil	Normal Copper Plating 300±100u"
		1/2OZ	2mil	2mil	
		1/3OZ	1.8mil	1.8mil	
	Double side	1OZ	3mil	3mil	
		1/2OZ	2.5mil	2.5mil	
		1/3OZ	2mil	2mil	
	1/3OZ	1.8mil	1.8mil	Only PTH Cu	
Coverlay/Stiffener					
Stiffener	Material type	Tolerance	Special tolerance	Remark	
	CVL	±0.3mm	±0.2mm	CVL Spilled glue≤0.10mm Minimum SUS size3mm X 5mm	
	PI,FR4				
	SUS				
	Adhesive				
Coverlay	Material type	Minimum Opening	Minimum space from Opening to inner pattern		
	CVL	0.5mm	0.30mm		
Printing					
Printing	Project	Project	Normal	Minimum	Remark
	Silkscreen	Tolerance	±0.3mm	±0.2mm	The color is specified by the customer
		Minimum	0.12mm	0.1mm	
		Height	1.0mm	0.8mm	
	Solder Mask Hot bake	Tolerance	±0.35mm	±0.3mm	
		Thickness	20±10um		
	Solder Mask development	Deviation	±0.075mm	±0.05mm	
		Mask spacing	0.1mm(min)		
		Minimum Opening	0.4mm X 0.4mm		
		Thickness	20±10um		
Punching					
Project	Project	Normal Tolerance	Minimum Tolerance	Remark	
Etching	Pitch to Pitch	±0.3mm	±0.2mm	The smallest tolerances require precision molding	
	Total Pitch(≤50mm)	±0.3mm	±0.2mm		
Punching	First Gold Finger Pin to Dimensions	±0.01mm	±0.05mm		
	Gold Finger to Dimensions	±0.075mm	±0.05mm		
	Dimensions	0.1mm			
	Minimum Angle R	0.2mm	0.15mm		
	NPTH to NPTH	±0.075mm	±0.05mm		
	NPTH to Dimensions	1.5mm	1.0mm		
	Trace to Dimensions	0.2mm			
	Minimum Punching hole	0.5mm			
	NPTH Tolerance	±0.5mm			
Surface Treament					
Project	Project	Ni/Au	spec	Characteristic	
Hard gold plating	Normal	Ni	2um~6um		
		Au	0.025~0.075um or 0.05um(min)		
	Thick Gold	Au	0.2um~0.8um		
Immersion gold	Normal	Ni	0.75um~2um		
		Au	0.025~0.075um		
OSP	thickness	OSP	0.2um~0.5um		
Thickness					
Board thickness tolerance	1L、2L	±0.03mm(±10%)			
	3L or more	±0.05mm(±10%)			